

Outgassing Compliant Power Inductors AE619PYA



- High temperature materials allow operation in ambient temperatures up to 155°C
- Passes NASA low outgassing specifications
- Tin-lead (Sn-Pb) termination for the best possible board adhesion
- High current and very low DCR
- Soft saturation makes them ideal for VRM/VRD applications.

Core material Composite

Terminations Tin-lead (63/37) over copper.

Weight 9.5 – 11.7 g

Ambient temperature –55°C to +105°C with Irms current.

Maximum part temperature +155°C (ambient + temp rise).

Storage temperature Component: –55°C to +155°C.

Tape and reel packaging: –55°C to +80°C

Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C / 85% relative humidity)

Enhanced crush-resistant packaging 300/13" reel

Plastic tape: 32 mm wide, 0.3 mm thick, 24 mm pocket spacing, 8.26 mm pocket depth

Part number ¹	Inductance ² ±20% (µH)	DCR (mOhms) ³		SRF (MHz) ⁴		Isat ⁵ (A)	Irms (A) ⁶	
		typ	max	min	typ		20°C rise	40°C rise
AE619PYA401MSZ	0.40	0.50	0.70	42.4	53.0	111	35.3	45.0
AE619PYA741MSZ	0.74	0.72	0.86	28.1	35.1	86.0	32.4	44.8
AE619PYA102MSZ	1.0	0.93	1.12	24.0	30.0	73.5	30.5	43.1
AE619PYA132MSZ	1.3	1.15	1.38	21.0	26.2	65.0	26.0	35.0
AE619PYA182MSZ	1.8	1.61	1.93	17.0	21.3	57.0	24.9	32.9
AE619PYA202MSZ	2.0	1.91	2.29	16.1	20.1	51.0	22.1	29.9
AE619PYA302MSZ	3.0	2.62	3.10	12.8	16.0	43.0	19.2	25.8
AE619PYA452MSZ	4.5	3.82	4.58	10.0	12.5	34.2	15.3	20.3
AE619PYA532MSZ	5.3	4.35	5.22	9.4	11.8	33.0	14.6	19.9
AE619PYA612MSZ	6.1	5.66	6.79	9.4	11.7	31.0	12.7	17.0

1. When ordering, please specify **testing** code:

AE619PYA822MSZ

Testing: Z = Unscreened
H = Group A screening per Coilcraft CP-SA-10001
All screening performed to the document's latest revision
Custom screening also available

2. Inductance tested at 100 kHz, 0.1 Vrms using an Agilent/HP 4192A.
3. DCR measured using a micro-ohmmeter.
4. SRF measured using an Agilent/HP 4395A or equivalent.
5. DC current at 25°C that causes an inductance drop of 30% (typ) from its value without current.
6. Current that causes the specified temperature rise from 25°C ambient. This information is for reference only and does not represent absolute maximum ratings.
7. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.

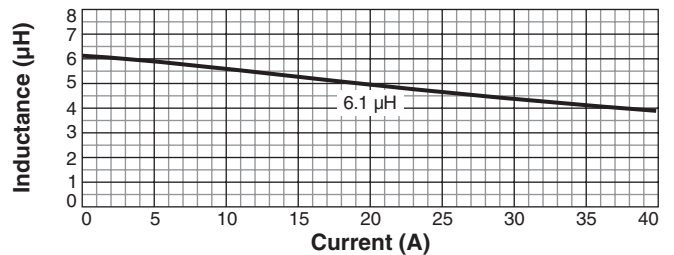
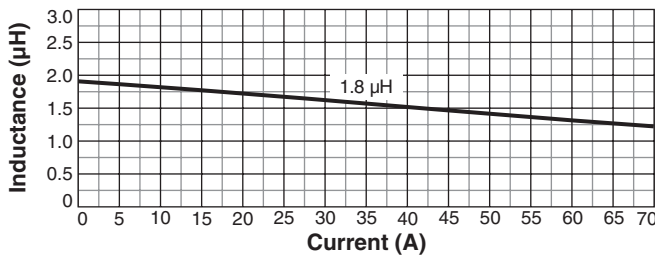
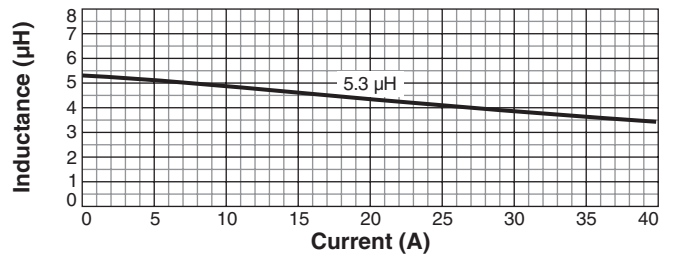
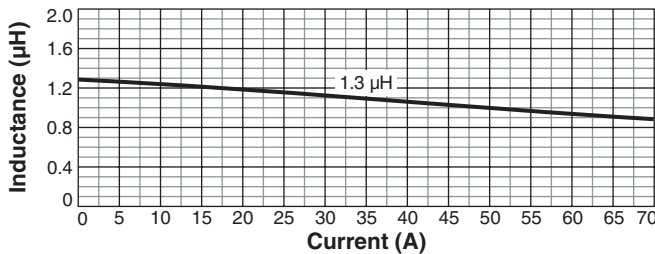
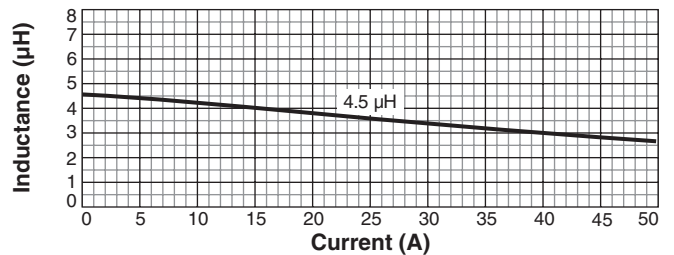
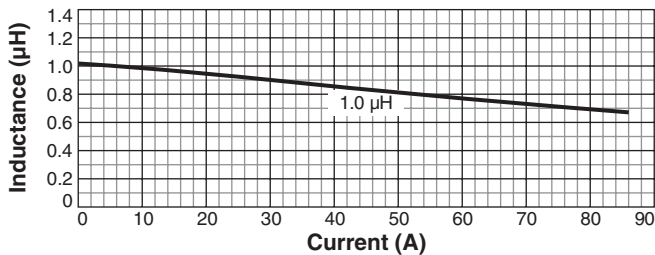
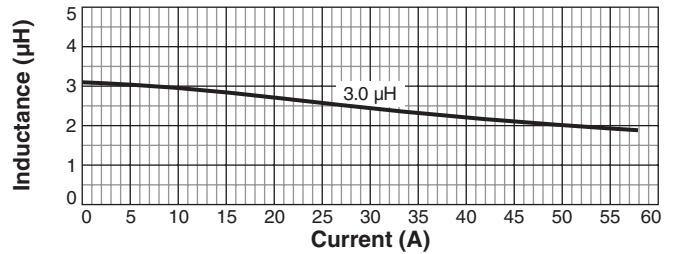
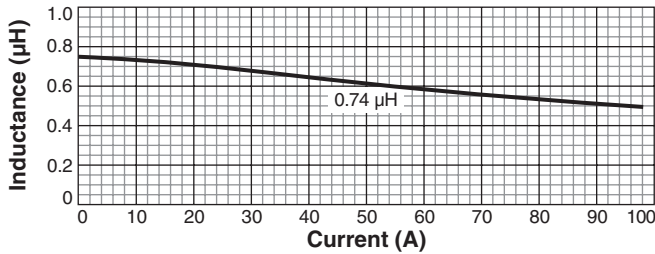
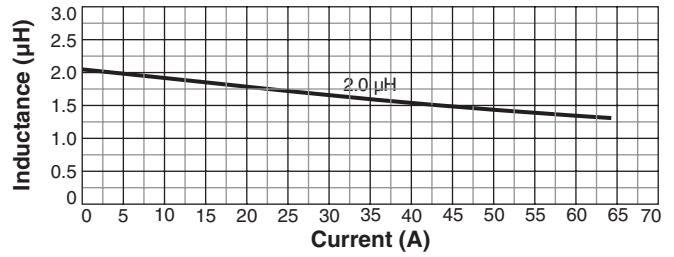
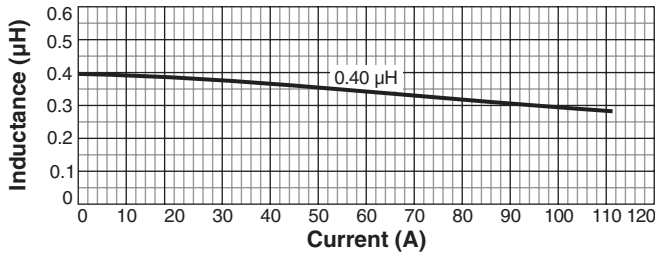
Irms Testing

Irms testing was performed on a 0.060" thick pcb with 4 oz. copper traces optimized to minimize additional temperature rise.

Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.

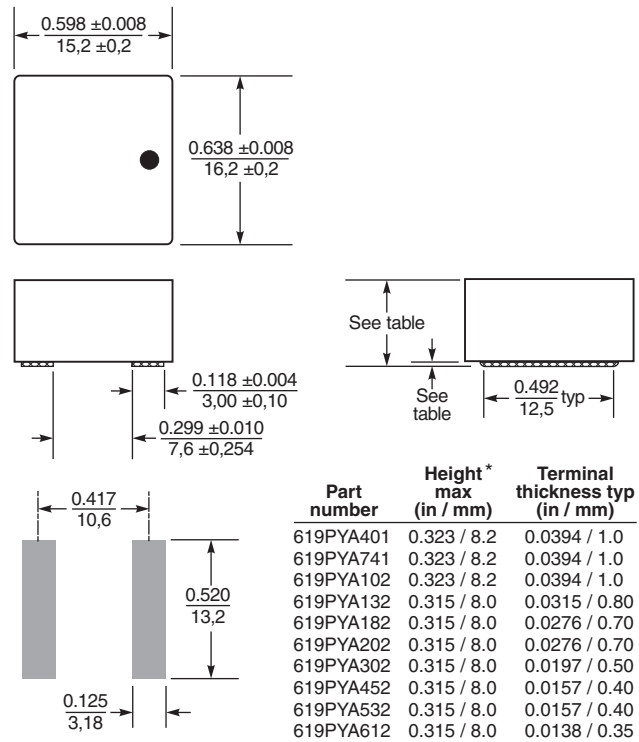
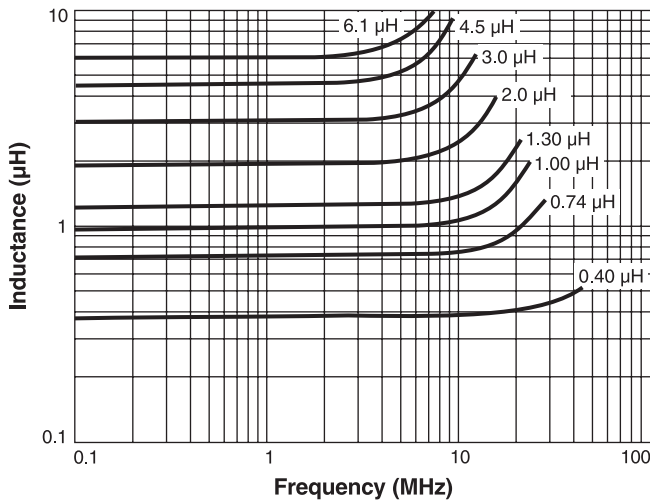
AE619PYA Series (1580)

L vs Current



AE619PYA Series (1580)

Typical L vs Frequency



Suggested Land Pattern

* Height dimension shown is for the mounted part after reflow. Dimension before mounting can be an additional 0.008 inch / 0,2 mm.

Dimensions are in $\frac{\text{inches}}{\text{mm}}$